

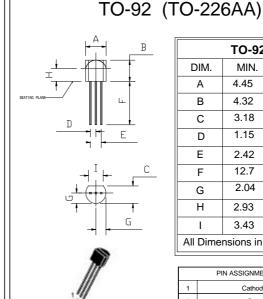
S1U50-A SERIES

Sensitive Gate Sillicon Controlled Rectifiers Reverse Blocking Thyristors

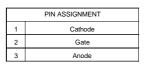
SCRs 1 AMPERES RMS 100 thru 600 VOLTS

FEATURES

- Sensitive Gate Allows Triggering by Microcontrollers and Other Logic Circuits
- Blocking Voltage to 600 Volts
- On- State Current Rating of 0.8 Amperes RMS at 80
- High Surge Current Capability 10 Amperes
- Minimum and Maximum Values of IGT, VGT and IH Specified for Ease of Design
- Immunity to dV/dt 20 V/msec Minimum at 110
- Glass-Passivated Surface for Reliability and Uniformity
- Pb-Free Package



TO-92				
DIM.	MIN.	MAX.		
А	4.45	4.70		
В	4.32	5.33		
С	3.18	4.19		
D	1.15	1.39		
Е	2.42	2.66		
F	12.7			
G	2.04	2.66		
Н	2.93			
I	3.43			
All Dimensions in millimeter				



MAXIMUM RATINGS (Tj= 25 unless otherwise noticed)

Rating		Value	Unit
Peak Repetitive Off- State Voltage (TJ= -40 to 110 , Sine Wave, 50 to 60 Hz; Gate Open) S1U50100A S1U50200A S1U50400A S1U50600A S1U50700A	VDRM, VRRM	100 200 400 600 700	Volts
On-State RMS Current (Tc = 80) 180° Conduction Angles		1.0	Amp
Peak Non-Repetitive Surge Current (1/2 Cycle, Sine Wave, 60 Hz, T _J = 25)		10	Amps
Circuit Fusing Consideration (t = 8.3 ms)		0.415	A ² s
Forward Peak Gate Power (TA = 25 , Pulse Width 1.0 us)		0.1	Watt
Forward Average Gate Power (TA = 25 , t = 8.3 ms)		0.1	Watt
Forward Peak Gate Current (T _A = 25 , Pulse Width 1.0 us)		1.0	Amp
Reverse Peak Gate Voltage (T _A = 25 , Pulse Width 1.0 ms)		5	Volts
Operating Junction Temperature Range @ Rate VRRM and VDRM		-40 to +110	
Storage Temperature Range		-40 to +150	
Notice: (1) VDRM and VRRM for all types can be applied on a continuous basis. Ratings apply for	Rev	.2, Jun-2005, KT	XD05

Notice: (1) VDRM and VRRM for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded



THERMAL CHARACTERISTICS

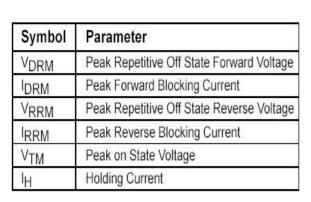
Characteristic		Value	Unit
Thermal Resistance - Junction to Case - Junction to Ambient	RthJC RthJA	75 150	/W
Maximum Lead Temperature for Soldering Purposes 1/16" from Case for 10 Seconds	TL	260	

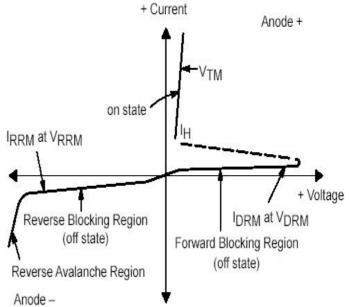
ELECTRICAL CHARACTERISTICS (T_C=25 unless otherwise noted)

Characteristics	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS					
Peak Reptitive Forward or Reverse Blocking Current (1) Tc=25 (VD=Rated VDRM and VRRM; RGK =1K Ohms) Tc=125	IDRM IRRM			10 100	uA
ON CHARACTERISTICS		•			
Peak Forward On-State Voltage @T _A =25 (I _{TM} =± 1.0A Peak, Pulse Width 1.0 ms, Duty Cycle 1%)	Vтм			1.7	Volts
Gate Trigger Current (Continuous dc) (2) Tc=25 (VAK = 7.0 Vdc; RL = 100 Ohms)	IGT		20	50	uA
Holding Current (VAK = 7.0 V, Initiating Current = 20 mA) T_{C} =25 T_{C} =-40	Ін		0.5	5.0 10	mA
Latch Current (VAK =7.0 V, Ig= 200 uA) Tc=25 Tc=-40	IL		0.6	10 15	mA
Gate Trigger Voltage (Continuous dc) TC= 25 (VD = 7.0 Vdc; RL = 100 Ohms) TC=-40	VGT		0.62	0.8 1.2	Volts
DYNAMIC CHARACTERISTICS					
Critical Rate of Rise of Off-State Voltage (VD=Rated VDRM,Exponential Waveform, PGK=1K Ohms, TJ=110	dv/dt	20	35		V/us
Repetitive Critical Rate of Rise of On-State Current IPK=20A,Pw=10 usec,diG/dt=1A/usex,Igt=20mA	di/dt			50	A/us

⁽¹⁾ RGK = 1000 Ohms included in measurement (2) Does not include RGK in measure







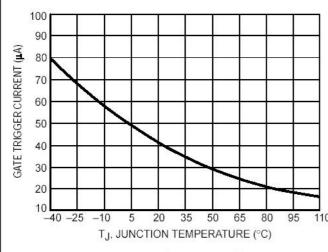


Figure 1. Typical Gate Trigger Current versus Junction Temperature

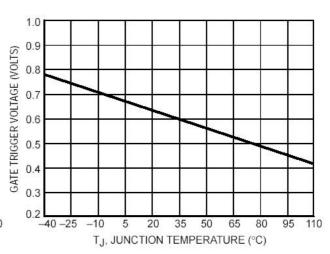


Figure 2. Typical Gate Trigger Voltage versus
Junction Temperature



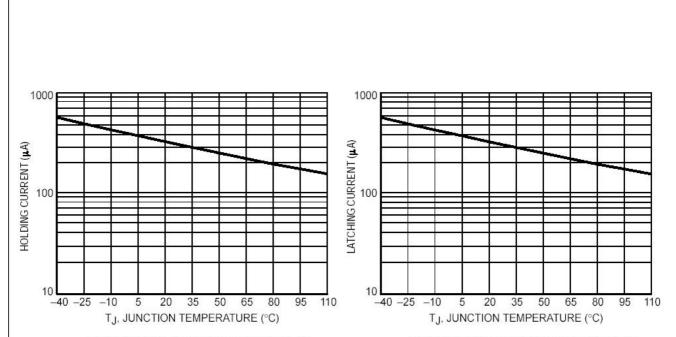


Figure 3. Typical Holding Current versus Junction Temperature

Figure 4. Typical Latching Current versus Junction Temperature

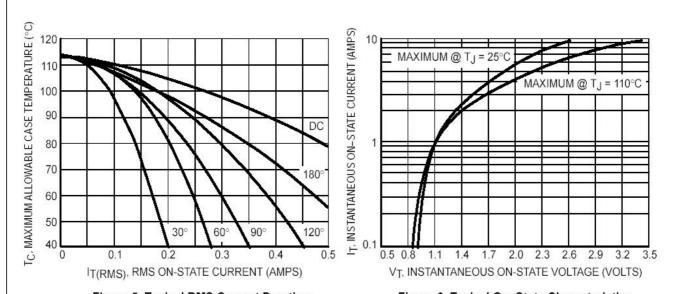


Figure 5. Typical RMS Current Derating

Figure 6. Typical On-State Characteristics